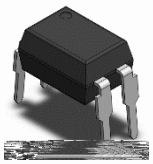
JOCMAXXC-D4P/S Series

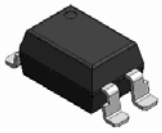
Rev.A.1.0

DESCRIPTION:

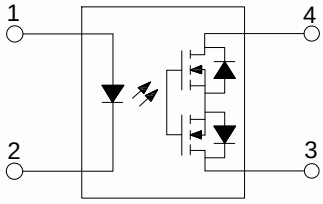
The products are 4-pin optical relays. The device consists of an AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit in a plastic DIP4 package with different lead forming options. The detector consists of a high-speed photovoltaic diode array and driver circuitry. The products are widely used in measuring and testing equipment, security and disaster prevention market, industrial machinery and equipment.



JOCMAXXC-D4P



JOCMAXXC-D4S



MAIN FEATURES

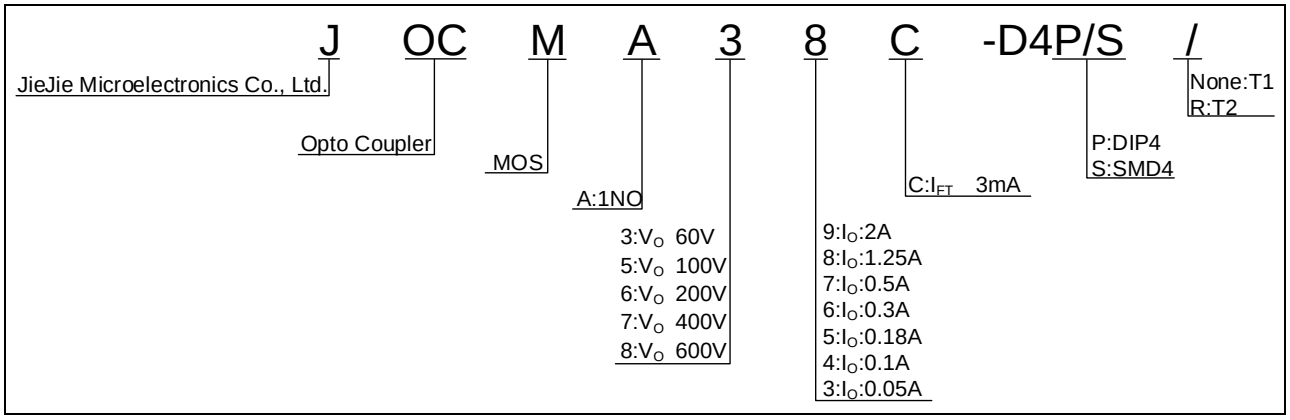
High isolation 5000 Vrms
Wide variation of load voltage 60V to 600V
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter			Symbol	Value	Unit
Input	Forward Current		I_F	50	mA
	Peak Forward Current		I_{FP}	1	A
	Reverse Voltage		V_R	6	V
	Input Power Dissipation		P_D	75	mW
Output	Load Voltage	JOCMA39C	V_O	60	V
		JOCMA38C		60	
		JOCMA58C		100	
		JOCMA67C		200	
		JOCMA66C		200	
		JOCMA75C		400	
		JOCMA74C		400	
		JOCMA83C		600	
	Continuous load current	JOCMA39C	I_O	2	A
		JOCMA38C		1.25	
		JOCMA58C		1.25	
		JOCMA67C		0.5	

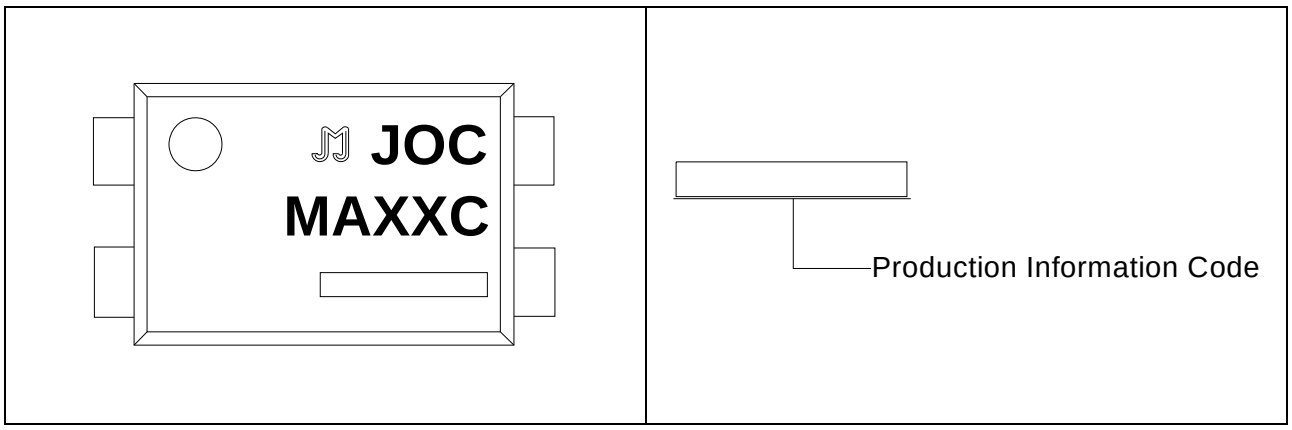
		JOCMA66C			-	0.25	0.5	
		JOCMA75C			-	0.23	0.5	
		JOCMA74C			-	0.21	0.5	
		JOCMA83C			-	0.18	0.5	
	Turn Off Time	JOCMA39C	t_{off}	I_F=5mA, I_O=Max.	-	0.2	1	ms
		JOCMA38C			-	0.2	1	
		JOCMA58C			-	0.2	1	
		JOCMA67C			-	0.2	1	
		JOCMA66C			-	0.2	1	
		JOCMA75C			-	0.2	1	
		JOCMA74C			-	0.2	1	
		JOCMA83C			-	0.2	1	

ORDERING INFORMATION



Packing Quantity			
Option	**Quantity**	**Quantity – Inner box**	**Quantity –Outer box**
DIP	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =32k Units
SMD	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =22.5k Units

MARKING



Characteristics Curves

FIG.1: LED Dropout Voltage vs. Ambient Temperature

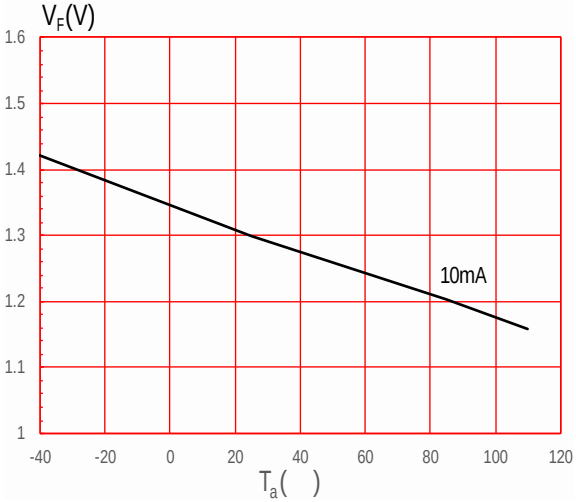


FIG.2: Output Current vs. Output Voltage

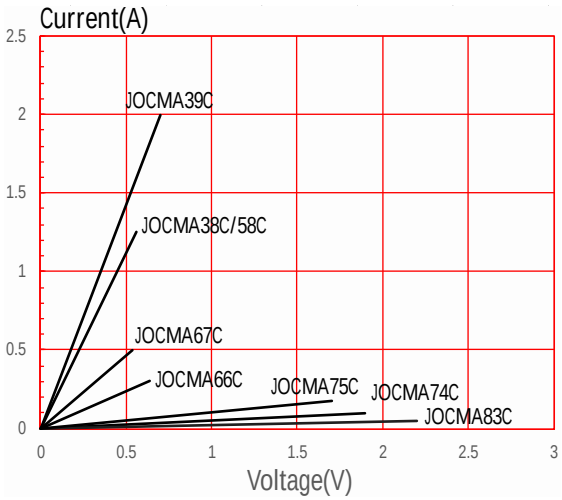


FIG.3: On Resistance vs. Ambient Temperature

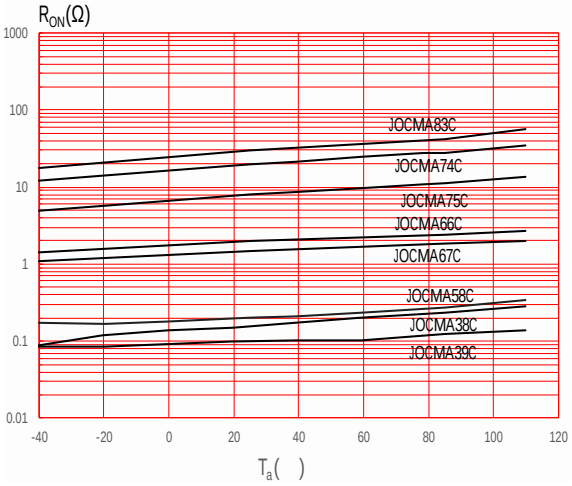


FIG.4: Load Current vs. Ambient Temperature

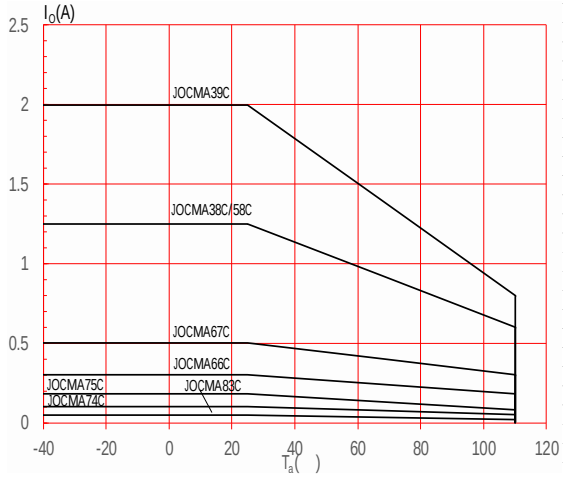


FIG.5: LED Operate Current vs. Ambient Temperature

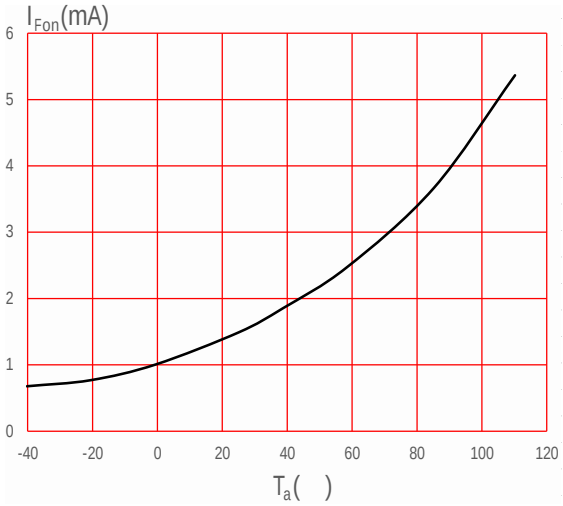


FIG.6: LED Turn Off Current vs. Ambient Temperature

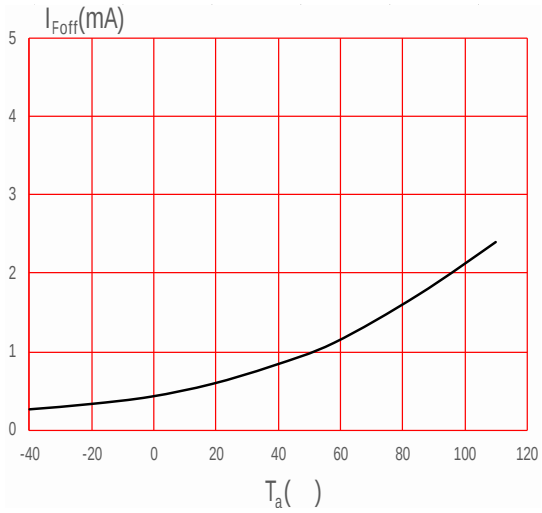


FIG.7: Turn On Time vs. Ambient Temperature

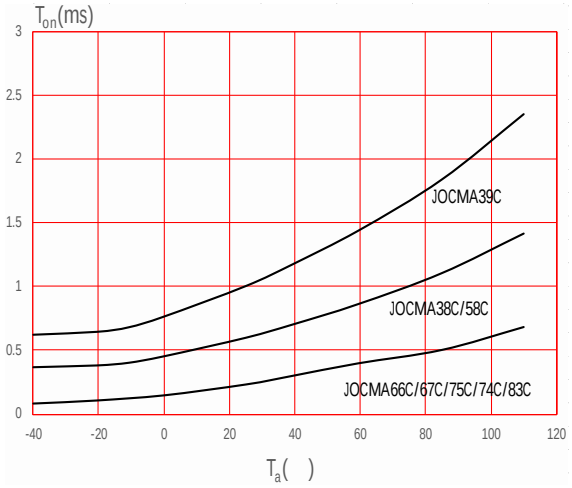


FIG.8: Turn Off Time vs. Ambient Temperature

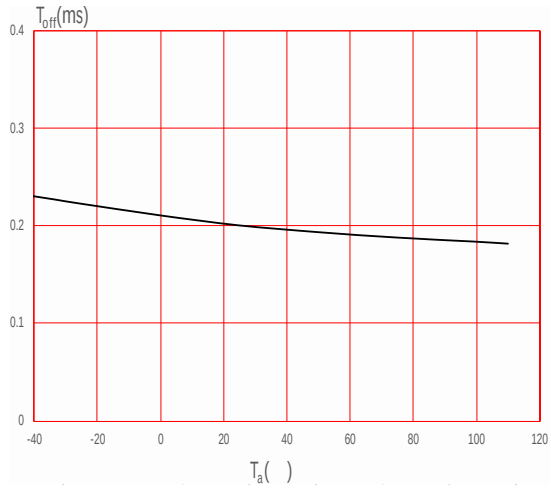


FIG.9: Turn On Time vs. LED Forward Current

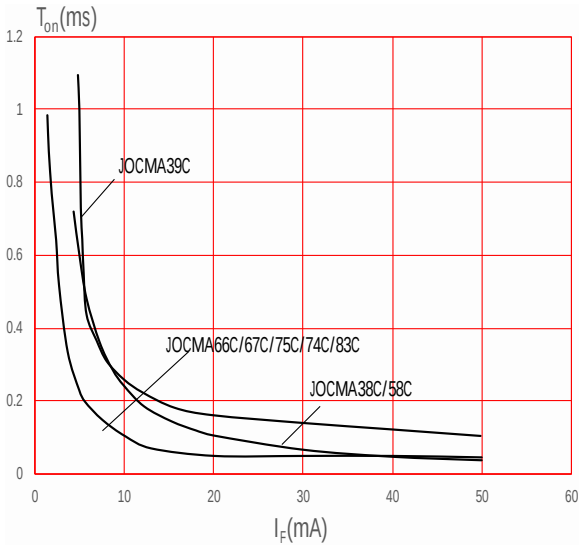


FIG.10: Turn Off Time vs. LED Forward Current

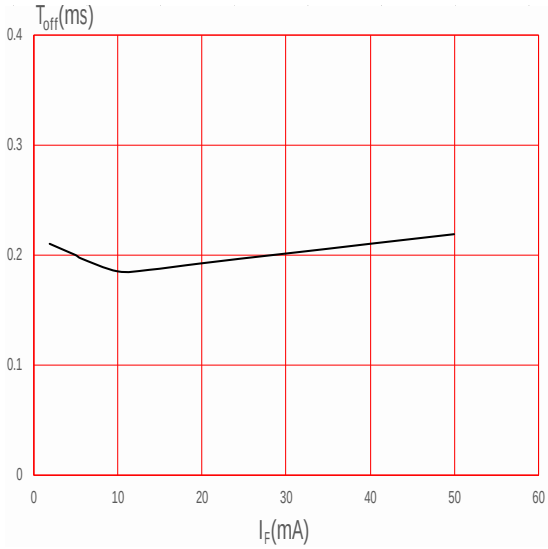


FIG.11: Off State Leakage Current vs. Load Voltage

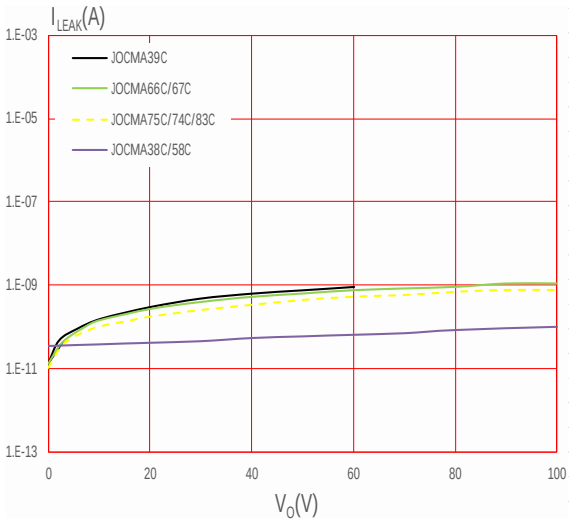
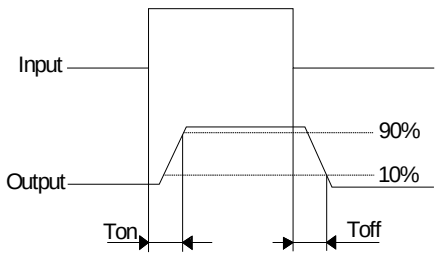
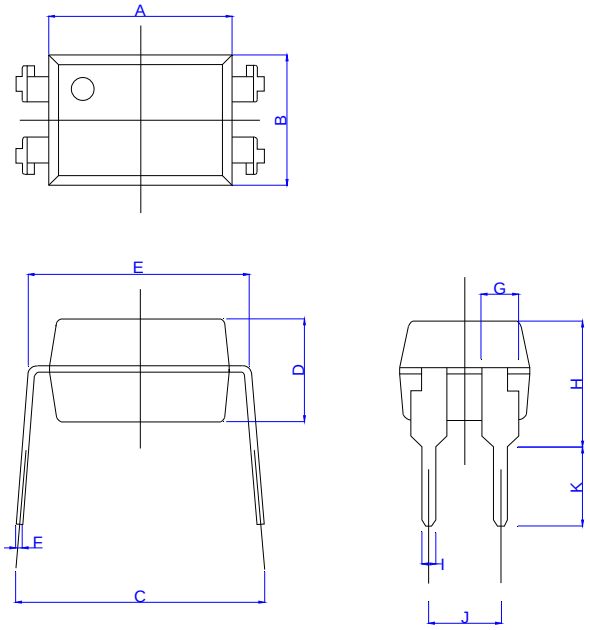


Fig.12: Turn on/Turn off time



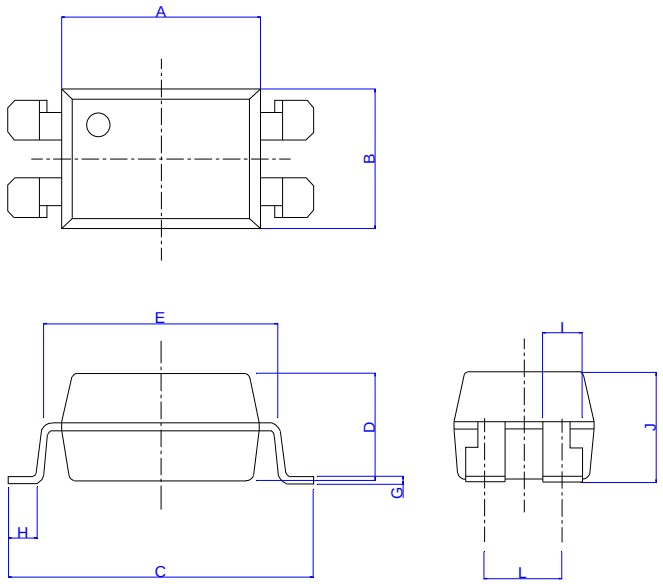
Package Dimension (Unit: mm)

Standard DIP Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.244		0.268
B	4.30		4.90	0.169		0.193
C	7.10		9.50	0.280		0.374
D	3.20		3.80	0.126		0.150
E	7.32		7.92	0.288		0.312
F	0.20		0.30	0.008		0.012
G	1.10		1.50	0.043		0.059
H	4.20		4.80	0.165		0.189
I	0.40		0.60	0.016		0.024
J	2.34		2.74	0.092		0.108
K	2.45		3.10	0.096		0.122

Option SMD Type:



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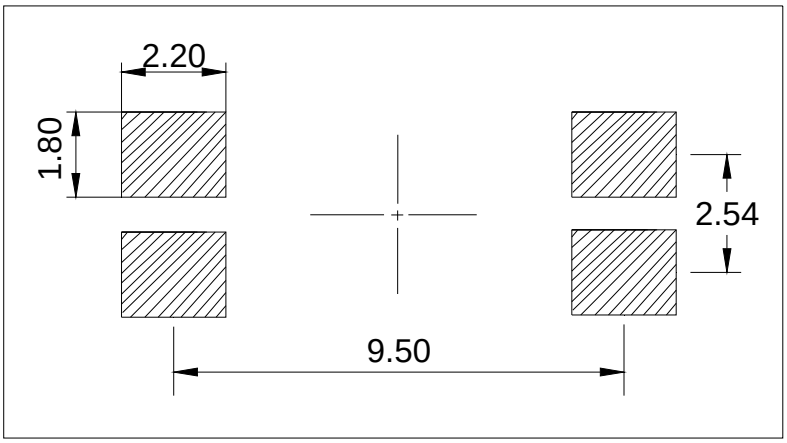
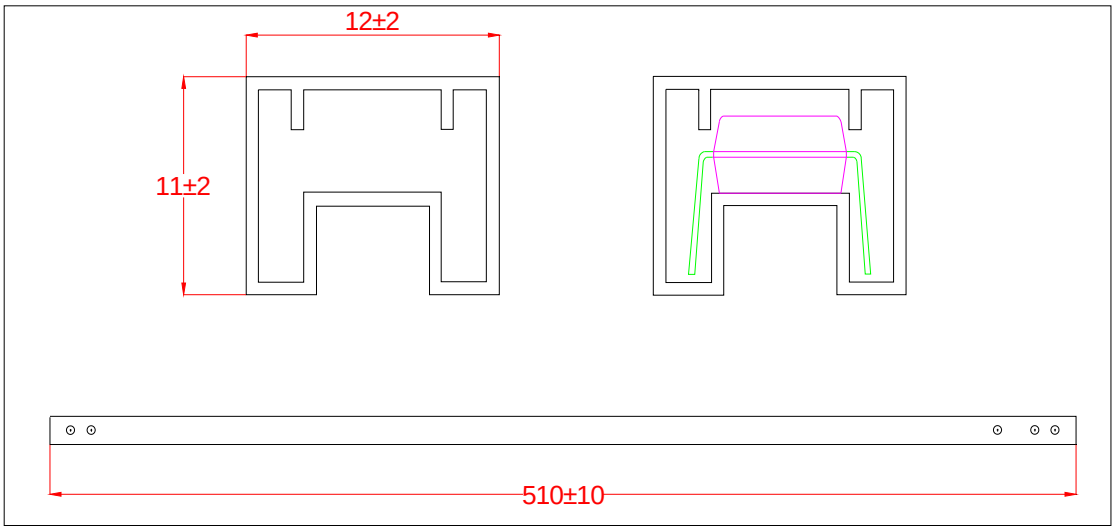
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Option SMD



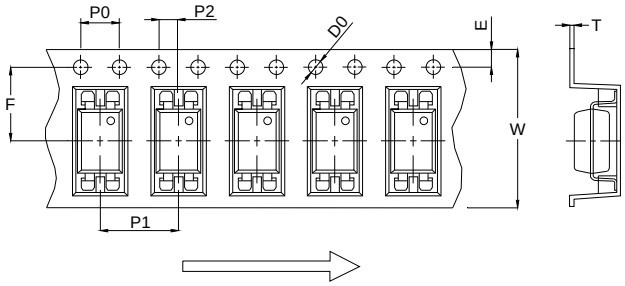
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

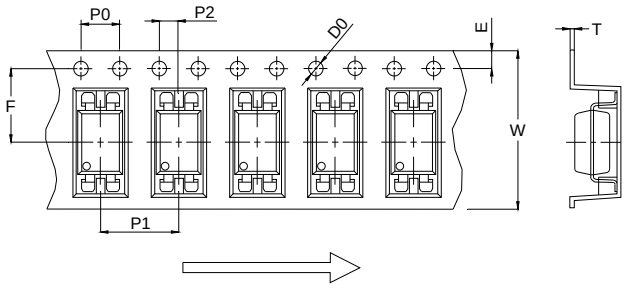


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None

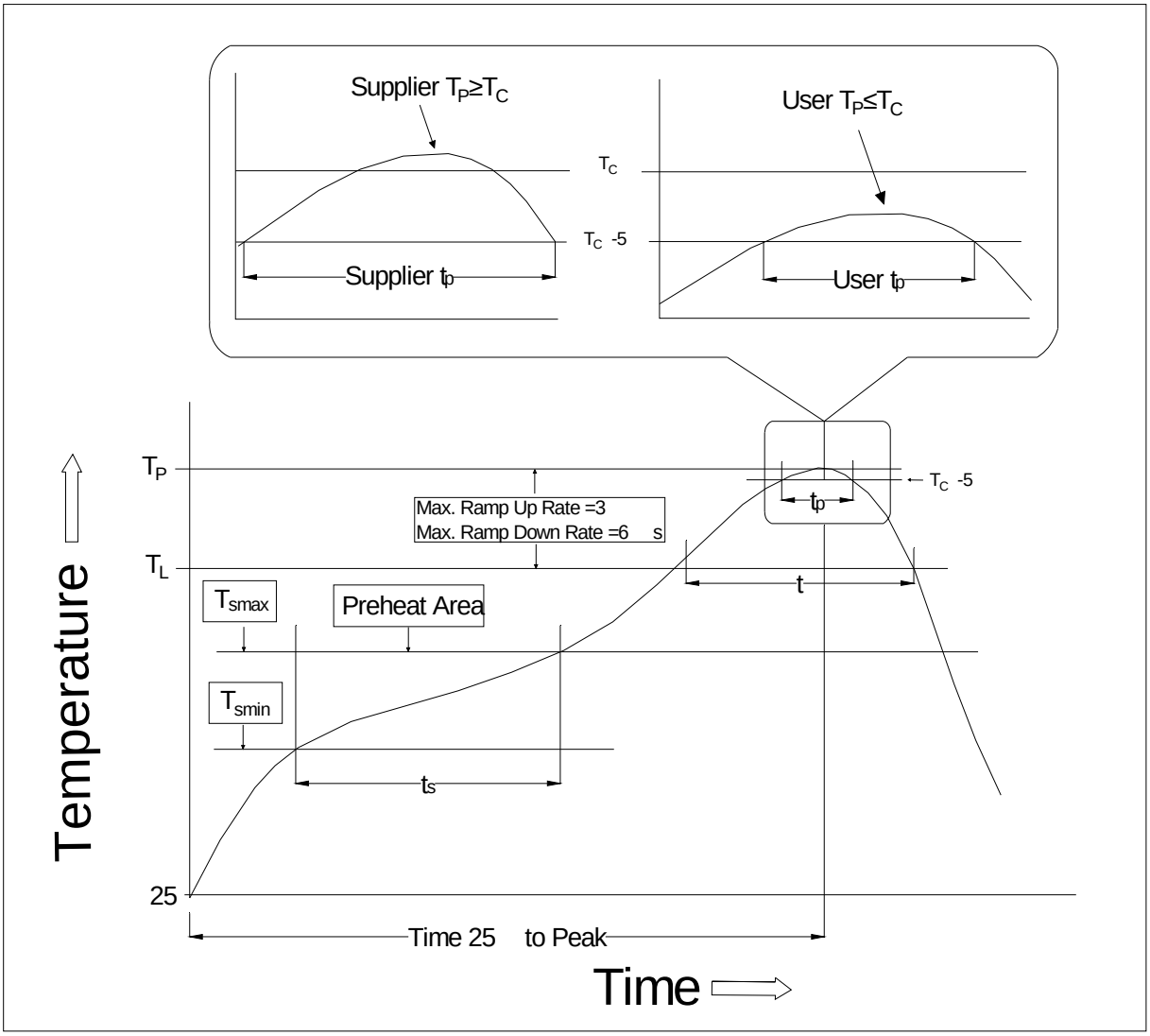


Option R



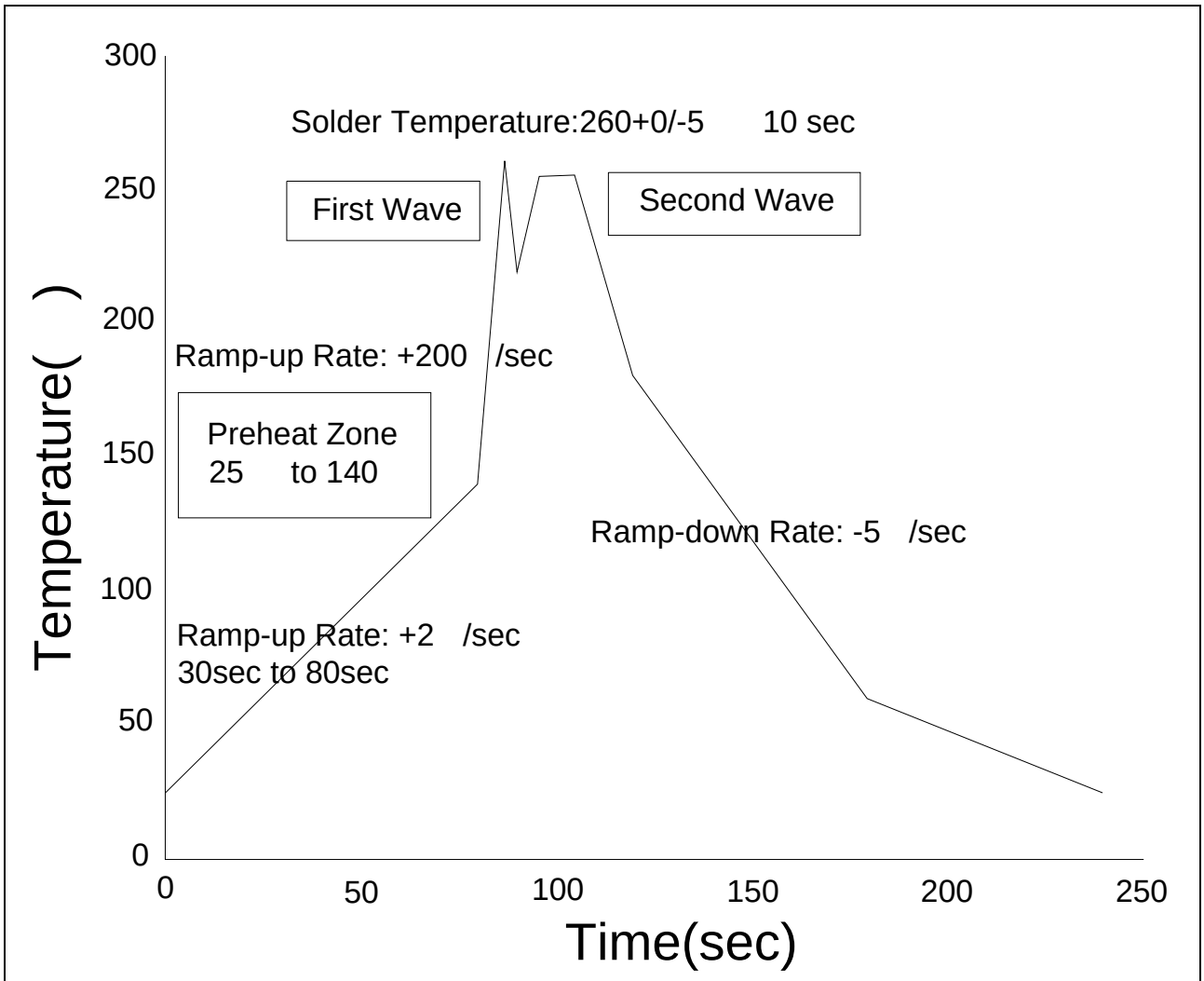
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.065
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

   Recommend storage humidity: <60%;

   MSL level: MSL 1

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